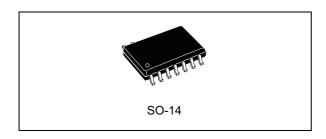


Half bridge gate driver

Datasheet - production data



Features

- High voltage rail up to 600 V
- dV/dt immunity ± 50 V/nsec in full temperature range
- Driver current capability:
 - 290 mA source.
 - 430 mA sink
- Switching times 75/35 nsec rise/fall with 1 nF load
- 3.3 V, 5 V CMOS/TTL input comparators with hysteresis
- Integrated bootstrap diode
- Uncommitted comparator
- Adjustable deadtime
- · Compact and simplified layout
- Bill of material reduction
- · Flexible, easy and fast design

Application

- · Motor driver for home appliances
- Factory automation
- · Industrial drives and fans
- HID ballasts
- Power supply units

Description

The L6393 is a high voltage device manufactured with the BCD™ "offline" technology. It is a single chip half bridge gate driver for the N-channel power MOSFET or IGBT.

The high-side (floating) section is designed to stand a voltage rail up to 600 V.

The logic inputs are CMOS/TTL compatible down to 3.3 V for the easy interfacing microcontroller/DSP.

The IC embeds an uncommitted comparator available for protections against overcurrent, overtemperature, etc.

Contents L6393

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L6393 Block diagram

1 Block diagram

Figure 1. Block diagram BOOTSTRAP DRIVER FLOATING STRUCTURE воот from LVG UV DETECTION UV DETECTION HVG DRIVER 13 LEVEL HVG PHASE SHIFTER LOGIC 12 OUT SHOOT THROUGH PREVENTION BRAKE V∝ρ LVG DRIVER LVG \overline{SD} CPOUT (COMPARATOR DEAD DT ПМЕ GND (

AM02393v1

Pin connection L6393

2 Pin connection

Figure 2. Pin connection (top view)

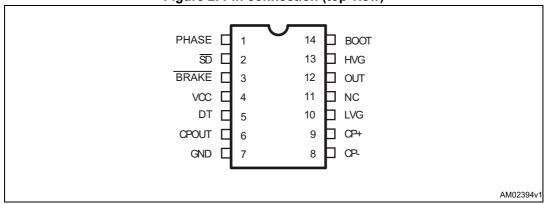


Table 1. Pin description

Pin no.	Pin name	Туре	Function
1	PHASE	1	Driver logic input (active high)
2	SD ⁽¹⁾	Ι	Shutdown input (active low)
3	BRAKE	I	Driver logic input (active low)
4	VCC	Р	Lower section supply voltage
5	DT	I	Deadtime setting
6	CPOUT	0	Comparator output (open drain)
7	GND	Р	Ground
8	CP-	I	Comparator negative input
9	CP+	1	Comparator positive input
10	LVG ⁽¹⁾	0	Low-side driver output
11	NC		Not connected
12	OUT	Р	High-side (floating) common voltage
13	HVG ⁽¹⁾	0	High-side driver output
14	воот	Р	Bootstrapped supply voltage

The circuit provides less than 1 V on the LVG and HVG pins (at I_{sink} = 10 mA), with V_{CC} > 3 V. This allows
omitting the "bleeder" resistor connected between the gate and the source of the external MOSFET
normally used to hold the pin low; the gate driver assures low impedance also in SD condition.

L6393 Truth table

3 Truth table

Table 2. Truth table

	Inputs	Outputs		
SD	PHASE	BRAKE	LVG	HVG
L	X ⁽¹⁾	X ⁽¹⁾	L	L
Н	L	L	Н	L
Н	L	Н	Н	L
Н	Н	L H		L
Н	Н	Н	L	Н

^{1.} X: don't care.

In the L6393 IC the two input signals PHASE and BRAKE are fed into an AND logic port and the resulting signal is in phase with the high-side output HVG and in opposition of phase with the low-side output LVG. This means that if BRAKE is kept to a high level, the PHASE signal drives the half bridge in phase with the HVG output and in opposition of phase with the LVG output. If BRAKE is set to a low level, the low-side output LVG is always ON and the high-side output HVG is always OFF, whatever the PHASE signal. This kind of logic interface provides the possibility to control the power stages using the PHASE signal to select the current direction in the bridge and the BRAKE signal to perform current slow decay on the low-sides.

From the point of view of the logic operations the two signals PHASE and BRAKE are completely equivalent, that means the two signals can be exchanged without any change in the behavior on the resulting output signals (see *Figure 1*).

Note:

The deadtime between the turn-OFF of one power switch and the turn-ON of the other power switch is defined by the resistor connected between the DT pin and the ground.

Electrical data L6393

4 Electrical data

4.1 Absolute maximum ratings

Table 3. Absolute maximum ratings

Symbol	Parameter	Va	Value			
Symbol	Parameter	Min.	Max.	Unit		
V _{CC}	Supply voltage	-0.3	21	V		
V _{OUT}	Output voltage	V _{BOOT} - 21	V _{BOOT} + 0.3	V		
V _{BOOT}	Bootstrap voltage	-0.3	620	V		
V _{hvg}	High-side gate output voltage	V _{OUT} - 0.3	V _{BOOT} + 0.3	V		
V _{Ivg}	V _{Ivg} Low-side gate output voltage		V _{CC} + 0.3	V		
V _{CP+}	Comparator positive input voltage	-0.3	V _{CC} + 0.3	V		
V _{CP-}	Comparator negative input voltage	-0.3	V _{CC} + 0.3	V		
Vi	Logic input voltage	-0.3	15	V		
V _{od}	Open drain voltage	-0.3	15	V		
dV _{OUT} /dt	Allowed output slew rate		50	V/ns		
P _{tot}	Total power dissipation (T _A = 25 °C)		800	mW		
T _J	Junction temperature		150	°C		
T _{STG}	Storage temperature	-50	-50 150			
ESD	Human body model		2			

4.2 Thermal data

Table 4. Thermal data

Symbol	Parameter	SO-14	Unit
R _{th(JA)}	Thermal resistance junction to ambient max.	120	°C/W

L6393 Electrical data

4.3 Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Pin	Parameter	Test condition	Min.	Max.	Unit
V _{CC}	4	Supply voltage		10	20	V
V _{BO} ⁽¹⁾	14 - 12	Floating supply voltage		9.8	20	V
V _{OUT}	12	DC output voltage		- 9 ⁽²⁾	580	V
V _{CP-}	8	Comparator negative input voltage	V _{CP+} ≤ 2.5 V		V _{CC} ⁽³⁾	V
V _{CP+}	9	Comparator positive input voltage	V _{CP-} ≤ 2.5 V		V _{CC} ⁽³⁾	V
f _{sw}		Switching frequency	HVG, LVG load C _L = 1 nF		800	kHz
TJ		Junction temperature		-40	125	°C

^{1.} $V_{BO} = V_{BOOT} - V_{OUT}$

^{2.} LVG off. V_{CC} = 10 V. Logic is operational if V_{BOOT} > 5 V, refer to AN2785 for more details.

^{3.} At least one of the comparator's input must be lower than 2.5 V to guarantee proper operation.

Electrical characteristics L6393

5 Electrical characteristics

5.1 AC operation

Table 6. AC operation electrical characteristics (V_{CC} = 15 V, T_{J} = +25 °C)

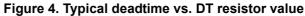
Symbol	Pin	Parameter	Test condition	Min.	Тур.	Max.	Unit	
AC opera	ation							
t _{on}	1, 3 vs.	High/low-side driver turn- on propagation delay		50	125	200	ns	
t _{off}	10, 13	High/low-side driver turn- off propagation delay	$V_{OUT} = 0 V$ $V_{BOOT} = V_{CC}$ $C_{L} = 1 \text{ nF}$	50	125	200	ns	
t _{sd}	2 vs. 10, 13	Shutdown to high/low-side propagation delay	V _i = 0 to 3.3 V see <i>Figure 3</i>	50	125	200	ns	
МТ		Delay matching, HS and LS turn-on/off	See Figure 3			30	ns	
			R _{DT} = 0, C _L = 1 nF	0.1	0.18	0.25		
DT	5	Deadtime setting range ⁽¹⁾	$R_{DT} = 37 \text{ k}\Omega, C_L = 1 \text{ nF}, C_{DT} = 100 \text{ nF}$	0.48	0.6	0.72		
וט	5	Deadline selling range.	R_{DT} = 136 k Ω , C_L = 1 nF, C_{DT} = 100 nF	1.35	1.6	1.85	μs	
			R_{DT} = 260 k Ω , C_L = 1 nF, C_{DT} = 100 nF	2.6	3.0	3.4		
			$R_{DT} = 0 \Omega$; $C_L = 1 nF$			80		
MDT		Matching doodtime (2)	$R_{DT} = 37 \text{ k}\Omega; C_L = 1 \text{ nF}; C_{DT} = 100 \text{ nF}$			120		
ו טוא	MDT	Matching deadtime ⁽²⁾	Matching deadtime V	$R_{DT} = 136 \text{ k}\Omega; C_L = 1 \text{ nF}; C_{DT} = 100 \text{ nF}$			250	ns
			$R_{DT} = 260 \text{ k}\Omega; C_L = 1 \text{ nF}; C_{DT} = 100 \text{ nF}$			400		
t _r	10 12	Rise time	C _L = 1 nF		75	120	ns	
t _f	10, 13	Fall time	C _L = 1 nF		35	70	ns	

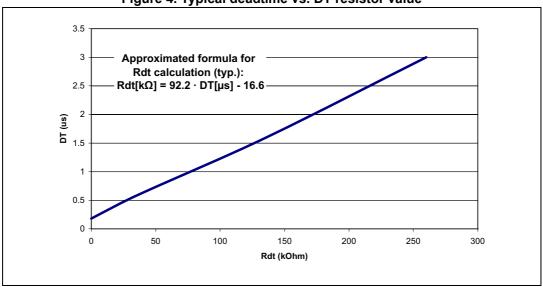
^{1.} See Figure 4.

^{2.} MDT = I DT_{LH} - DT_{HL} I see *Figure 5 on page 12*.

PHASE BRAKE HVG t_{on} $t_{
m off}$ PHASE BRAKE LVG toff t_{on} $\overline{\mathsf{SD}}$ t_{f} LVG/HVG $\boldsymbol{t}_{\text{sd}}$

Figure 3. Timing





Electrical characteristics L6393

5.2 DC operation

Table 7. DC operation electrical characteristics (V_{CC} = 15 V; T_J = +25 °C)

Symbol	Pin	Parameter	Test condition	Min.	Тур.	Max.	Unit
Low supply	/ voltage	e section		•	•	•	
V _{CC_hys}		V _{CC} UV hysteresis		1.2	1.5	1.8	V
V _{CC_thON}		V _{CC} UV turn-ON threshold		9	9.5	10	V
V _{CC_thOFF}		V _{CC} UV turn-OFF threshold		7.6	8	8.4	V
I _{QCCU}	4	Undervoltage quiescent supply current	$V_{CC} = 7 \text{ V}; \overline{SD} = 5 \text{ V}; PHASE}$ and BRAKE = GND; $R_{DT} = 0 \Omega; CP + = GND;$ CP - = 0.5 V		110	150	
Iqcc		Quiescent current	V_{CC} = 15 V; \overline{SD} = 5 V; PHASE and BRAKE = GND; R_{DT} = 0 Ω ; CP + = GND; CP - = 0.5 V		600	1000	μА
Bootstrapp	ed supp	ly voltage section ⁽¹⁾					
V _{BO_hys}		V _{BO} UV hysteresis		0.8	1.0	1.2	V
V _{BO_thON}	N	V _{BO} UV turn-ON threshold		8.2	9	9.8	V
V _{BO_thOFF}		V _{BO} UV turn-OFF threshold		7.3	8	8.7	V
I _{QBOU}	14	Undervoltage V _{BOOT} quiescent current	V_{BO} = 7 V \overline{SD} = 5 V; PHASE and BRAKE = 5 V; R _{DT} = 0 Ω ; CP + = GND; CP - = 0.5 V		40	100	
I _{QBO}		V _{BOOT} quiescent current	V_{BO} = 15 V \overline{SD} = 5 V; PHASE and BRAKE = 5 V; R _{DT} = 0 Ω ; CP + = GND; CP - = 0.5 V		140	210	μΑ
I _{LK}		High voltage leakage current	V _{hvg} = V _{OUT} = V _{BOOT} = 600 V			10	
R _{DSon}		Bootstrap driver on resistance ⁽²⁾	LVG ON		120		Ω
Driving buf	fers sec	tion	,	1	1	1	
I _{so}	10.40	High/low-side source short-circuit current	$V_{IN} = V_{ih} (t_p < 10 \ \mu s)$	200	290		mA
I _{si}	10, 13	High/low-side sink short-circuit current	$V_{IN} = V_{il} (t_p < 10 \mu s)$	250	430		mA
Logic input	ts			•		•	
V _{il}	1 2 2	Low level logic threshold voltage		0.8		1.1	V
V _{ih}	1, 2, 3	High level logic threshold voltage		1.9		2.25	V
	1	I.	1	-1			



			(00 / 0	<i>,</i> ,		,	
Symbol	Pin	Parameter	Test condition	Min.	Тур.	Max.	Unit
I _{PHASEh}	1	PHASE logic "1" input bias current	PHASE = 15 V	20	40	100	
I _{PHASEI}	'	PHASE logic "0" input bias current	PHASE = 0 V			1	
I _{BRAKEh}	3	BRAKE logic "1" input bias current	BRAKE = 15 V	20	40	100	
I _{BRAKEI}	3	BRAKE logic "0" input bias current	BRAKE = 0 V			1	μA
I _{SDh}	2	SD logic "1" input bias current	SD = 15 V	10	30	100	
I _{SDI}	2	SD logic "0" input bias current	SD = 0 V			1	

Table 7. DC operation electrical characteristics (V_{CC} = 15 V; T_J = +25 °C) (continued)

Table 8. Sense comparator ($V_{CC} = 15 \text{ V}, T_J = +25 \text{ °C}$)⁽¹⁾

Symbol	Pin	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{io}	8, 9	Input offset voltage		-15		15	mV
I _{ib}	0, 9	Input bias current	V _{CP+} = 1 V			1	μA
V _{ol}	6	Open drain low level output voltage	I _{od} = - 3 mA			0.5	٧
t _{d_comp}		Comparator delay $ \begin{array}{c} R_{pu} = 100 \text{ k}\Omega \text{ to 5 V;} \\ V_{CP-} = 0.5 \text{ V} \end{array} $			90	130	ns
SR	6	Slew rate	$C_L = 180 \text{ pF}, R_{pu} = 5 \text{ k}\Omega$		60		V/µs

^{1.} The comparator is disabled when $V_{\mbox{\footnotesize{CC}}}$ is in UVLO condition.

^{1.} $V_{BO} = V_{BOOT} - V_{OUT}$

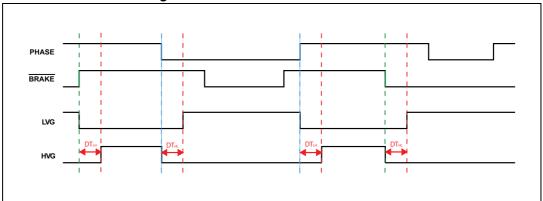
^{2.} R_{DSon} is tested in the following way: $R_{DSon} = [(V_{CC} - V_{BOOT1}) - (V_{CC} - V_{BOOT2})] / [I_1(V_{CC}, V_{BOOT1}) - I_2(V_{CC}, V_{BOOT2})]$ where I_1 is the pin 14 current when $V_{BOOT} = V_{BOOT1}$, I_2 when $V_{BOOT} = V_{BOOT2}$.

Waveform definition L6393

6 Waveform definition

12/19

Figure 5. Deadtime waveform definition



7 Typical application diagram

BOOTSTRAP DRIVER BOOT \pm from LVG UV DETECTION UV DETECTION HVG DRIVER LEVEL SHIFTER PHASE LOGIC SHOOT THROUGH PREVENTION BRAKE 12 OUT TO LOAD LVG DRIVER LVG SD CPOUT COMPARATOR CP-DT DEAD ПМЕ GND AM02395v1

Figure 6. Application diagram

Bootstrap driver L6393

8 Bootstrap driver

A bootstrap circuitry is needed to supply the high voltage section. This function is normally accomplished by a high voltage fast recovery diode (*Figure 7.a*). In the L6393 device a patented integrated structure replaces the external diode. It is realized by a high voltage DMOS, driven synchronously with the low-side driver (LVG), with a diode in series, as shown in *Figure 7.b*. An internal charge pump (*Figure 7.b*) provides the DMOS driving voltage.

CBOOT selection and charging

To choose the proper C_{BOOT} value the external MOSFET can be seen as an equivalent capacitor. This capacitor C_{EXT} is related to the MOSFET total gate charge:

Equation 1

$$C_{EXT} = \frac{Q_{gate}}{V_{gate}}$$

The ratio between the capacitors C_{EXT} and C_{BOOT} is proportional to the cyclical voltage loss. It has to be:

E.g.: if Q_{gate} is 30 nC and V_{gate} is 10 V, C_{EXT} is 3 nF. With C_{BOOT} = 100 nF the drop would be 300 mV.

If HVG has to be supplied for a long time, the C_{BOOT} selection has to take into account also the leakage and quiescent losses.

E.g.: HVG steady state consumption is lower than 200 μ A, so if HVG T_{ON} is 5 ms, C_{BOOT} has to supply 1 μ C to C_{EXT}. This charge on a 1 μ F capacitor means a voltage drop of 1 V.

The internal bootstrap driver gives a great advantage: the external fast recovery diode can be avoided (it usually has a great leakage current).

This structure can work only if V_{OUT} is close to GND (or lower) and in the meanwhile the LVG is on. The charging time (T_{charge}) of the C_{BOOT} is the time in which both conditions are fulfilled and it has to be long enough to charge the capacitor.

The bootstrap driver introduces a voltage drop due to the DMOS R_{DSon} (typical value: 120 Ω). At low frequency this drop can be neglected. Anyway increasing the frequency it must be taken in to account.

The following equation is useful to compute the drop on the bootstrap DMOS:

Equation 2

$$V_{drop} = I_{charge}R_{dson} \rightarrow V_{drop} = \frac{Q_{gate}}{T_{charge}}R_{dson}$$

where Q_{gate} is the gate charge of the external power MOSFET, R_{DSon} is the on resistance of the bootstrap DMOS, and T_{charge} is the charging time of the bootstrap capacitor.

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L6393 Bootstrap driver

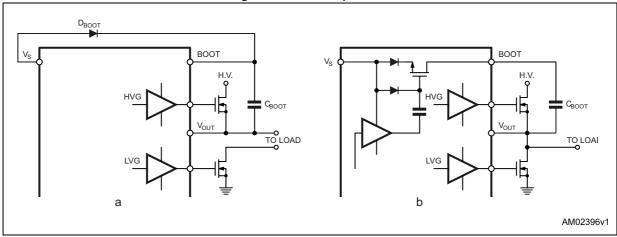
For example: using a power MOSFET with a total gate charge of 30 nC the drop on the bootstrap DMOS is about 1 V, if the T_{charge} is 5 μs . In fact:

Equation 3

$$V_{drop} \,=\, \frac{30nC}{5\mu S} \cdot 120\Omega \sim 0.7 V$$

 V_{drop} has to be taken into account when the voltage drop on C_{BOOT} is calculated: if this drop is too high, or the circuit topology doesn't allow a sufficient charging time, an external diode can be used.

Figure 7. Bootstrap driver



Package information L6393

9 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

SO-14 package information

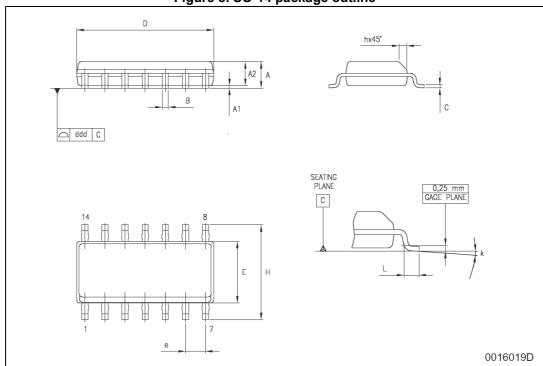


Figure 8. SO-14 package outline

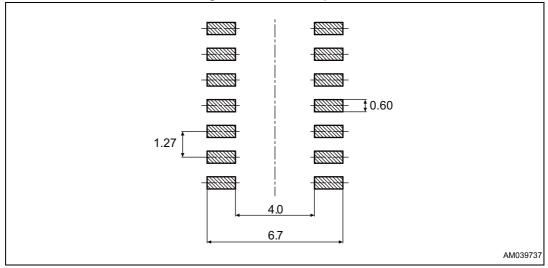
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L6393 Package information

Table 9. SO-14 package mechanical data

	Dimensions						
Symbol	mm			inch			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α			1.75			0.068	
a1	0.1		0.2	0.003		0.007	
a2			1.65			0.064	
b	0.35		0.46	0.013		0.018	
b1	0.19		0.25	0.007		0.010	
С		0.5			0.019		
c1		1	45° (t	yp.)	ı		
D	8.55		8.75	0.336		0.344	
E	5.8		6.2	0.228		0.244	
е		1.27			0.050		
e3		7.62			0.300		
F	3.8		4.0	0.149		0.157	
G	4.6		5.3	0.181		0.208	
L	0.5		1.27	0.019		0.050	
М			0.68			0.026	
S			8° (m	ax.)			

Figure 9. SO-14 footprint



Order codes L6393

10 Order codes

Table 10. Order codes

Order codes	Package	Packaging
L6393D	L6393D SO-14	
L6393DTR	30-14	Tape and reel

11 Revision history

Table 11. Document revision history

Date	Revision	Changes
03-Mar-2008	1	Initial release
18-Mar-2008	2	Cover page updated
17-Nov-2009	3	Updated: Cover page, Table 4 on page 6, Table 6 on page 7, Table 7 on page 8, Table 8 on page 10, Table 9 on page 11
11-Aug-2010	4	Updated: Table 1 on page 1, Table 5 on page 7 and Table 7 on page 10.
18-Sep-2015	5	Removed DIP-14 package from the entire document. Updated <i>Table 3 on page 6</i> (added ESD parameter and value, removed note below <i>Table 3</i>). Updated <i>Table 4 on page 6</i> (updated R _{th(JA)} value). Updated <i>Table 7 on page 10</i> (updated V _{il} and V _{ih} parameters and values, updated note 2. below <i>Table 7 -</i> replaced V _{CBOOTx} by V _{BOOTx}). Updated <i>Table 8 on page 11</i> (added conditions to title and note 1.). Named and numbered <i>Equation 1 on page 14</i> , <i>Equation 2 on page 14</i> and <i>Equation 3 on page 15</i> . Updated <i>Section 9 on page 16</i> (added/updated titles, reversed order of <i>Figure 8</i> and <i>Table 9</i> , updated header of <i>Table 9</i> , added <i>Figure 9</i>). Updated <i>Table 10 on page 18</i> (moved from page 1 to page 18, added and updated titles). Updated cross-references throughout document. Minor modifications throughout document.

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